

ABSTRACT**COMPOSITION FOR METAL ELECTROPLATING COMPRISING LEVELING AGENT**

A composition comprising a source of metal ions and at least one leveling agent comprising a linear or branched, polymeric imidazolium compound comprising the structural unit of formula L1 (L1) wherein R^1 , R^2 , R^3 are each independently selected from an H atom and an organic radical having from 1 to 20 carbon atoms, R^4 is a divalent, trivalent or multivalent organic radical which does not comprise a hydroxyl group in the α or β position relative to the nitrogen atom of the imidazole rings. n is an integer.

(Figure 3b)